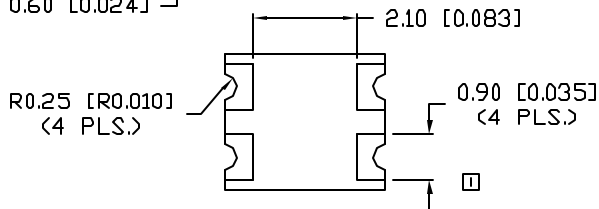
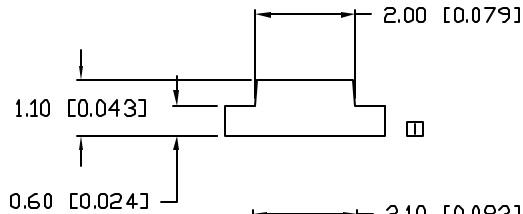
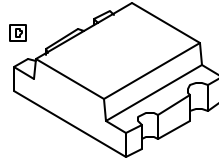
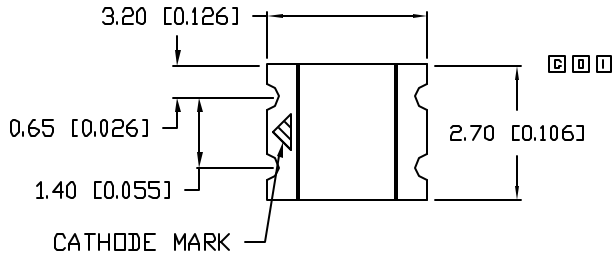
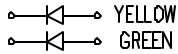
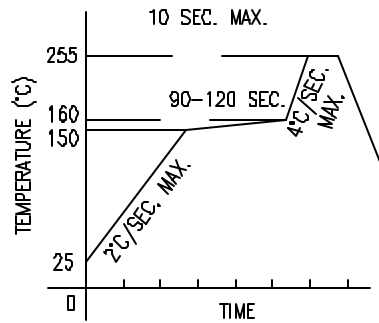


UNCONTROLLED DOCUMENT

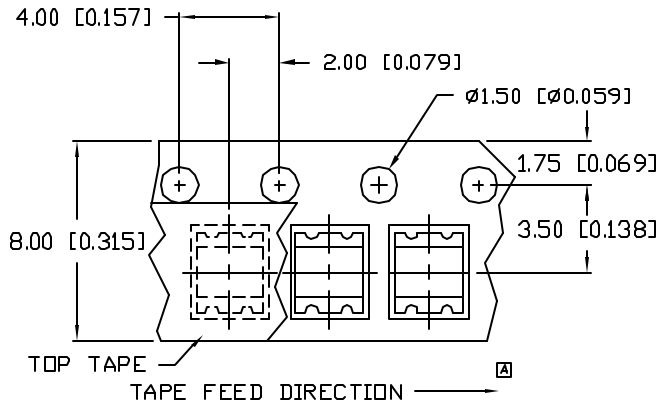
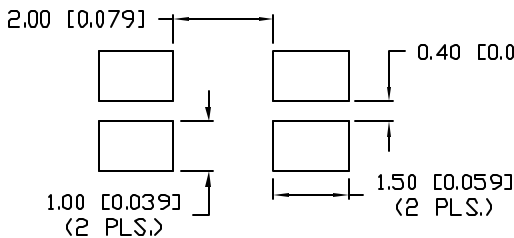


LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER		REV.
SML-LX1210YGC-TR		I
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	ADDED TAPE W/POLARITY AND DIRECTION.	11.6.95
B	E.C.N. #10324.	3.17.97
C	E.C.N. #10404, & #10BRDR & REDRAWN.	5.22.98
D	E.C.N. #10695	1.4.01
E	E.C.N. #10834.	1.24.02
F	E.C.N. #10972.	3.25.03
G	E.C.N. #11014.	7.11.03
H	E.C.N. #11148.	2.7.05
I	E.C.N. #11479.	2.22.08

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585 (YELLOW)		nm	
		565 (GREEN)		nm	
FORWARD VOLTAGE (Y/G)		2.1/2.2	2.5/2.6	V _f	
REVERSE VOLTAGE	5.0			V _r	I _r =100μA
AXIAL INTENSITY		10		md	I _f =20mA
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	YELLOW/GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		150	mA
STEADY CURRENT		25	mA
POWER DISSIPATION		65	mW
DERATE FROM 25°C		-1.2	mW/°C
OPERATING TEMP.		-25 TO +85	°C
STORAGE TEMP.		-30 TO +85	°C

* $t < 10\mu\text{s}$ NOTES:

1. THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.
2. LOCATION FOR CATHODE MARK CAN BE EITHER ON THE TOP OR BOTTOM OF THE PART.

CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=^{+DECIMAL PRECISION}_{-0.00} MAX.=^{+0.00}_{-DECIMAL PRECISION}

REV.	PART NUMBER
I	SML-LX1210YGC-TR
2.7mm x 3.2mm P.C.B. SURFACE MOUNT LED, DUAL YELLOW/GREEN CHIPS, WATER CLEAR LENS.	

CONFIDENTIAL INFORMATION
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RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

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JJD			PAGE: 1 OF 1
			SCALE: N/A